

CLEAN VERSION OF CLAIMS

1. An electronic component comprising at least one semiconductor chip having at least its electrodes formed exclusively on one surface thereof, and surfaces other than said one surface are continuously covered with a protective material.
2. The electronic component according to claim 1 wherein said protective material comprises an organic insulating resin or an inorganic insulating material.
3. The electronic component according to claim 1, comprising a semiconductor chip diced from a wafer at a position of said protective material for mounting on a package substrate, wherein said electrode is formed on said one surface, which is a device surface, of said semiconductor chip, and both a side wall and a bottom surface of said semiconductor chip are covered with said protective material.
4. The electronic component according to claim 3 wherein a solder bump is formed on said electrode.
5. The electronic component according to claim 1 wherein a plurality of different types of semiconductor chips are integrated and bonded by said protective material.
6. A pseudo wafer comprising a plurality of semiconductor chips each having at least their electrodes formed solely on one surface thereof, wherein interspaces between said plurality and/or said chips and bottom surfaces thereof are continuously covered with said protective material, and the chips are bonded with each other.

8. The pseudo wafer according to claim 6 wherein said plurality of semiconductor chips arrayed thereon are diced at a position of said protective material between said plurality of semiconductor chips and thereafter mounted on a packaging substrate.